Product / Process Change Notification



N° 2018-059-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Several Changes affecting Gen6.2 IGBT in TO247 packages

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before 21. August 2020.
- Infineon aligns with the widely-recognized JEDEC STANDARD "JESD46", which stipulates: "Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change."

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG Postal Address Headquarters: Am Campeon 1-15, D-85579 Neubiberg, Phone +49 (0)89 234-0 Chairman of the Supervisory Board: Dr. Wolfgang Eder Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Dr. Sven Schneider Registered Office: Neubiberg Commercial Register: München HRB 126492

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► **Products affected:** Please refer to attached affected product list 1_cip18059_A

Detailed Change Information:

Subject:	Several Changes affecting Gen6.2 IGBT in TO247 packages				
Reason:	The wafer production of the affected products will be transferred to Vanguard International Semiconductor and Infineon Technologies (Kulim) Sdn. Bhd., Kulim, Malaysia according to the global Infineon production strategy.				
Description:	<u>Old</u>	New			
Wafer Site FEOL	 Infineon Technologies Americas Corp., Temecula, United States 	 Vanguard International Semiconductor 			
Wafer Site BEOL	 Infineon Technologies Americas Corp., Temecula, United States 	 Infineon Technologies (Kulim) Sdn. Bhd., Kulim, Malaysia 			
Wafer Diameter	■ 6 inch	8 inch			
Assembly Changes Leadframe	 Mold locking features HEATSINK HOLE HOLE PAD BOND POST 	• Updated Mold locking features			
Final Test Location	 Infineon Technologies Americas Corp., Temecula, United States 	 Infineon Technologies (Kulim) Sdn. Bhd., Kulim, Malaysia 			
Product Identification:	Traceability assured via date code. No change in SP ordering number				

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Impact of Change:	Based on the qualification performed, Infineon does not see any negative impact on quality, function and reliability De Qu Ma Ids; SEM-PW-02,SEM-PW-06,SEM-PW-07,SEM-PW-08, SEM-PA-03, SEM-PW-13, SEM-TF-01
Attachments:	Affected product list 1_cip18059_A
Time Schedule:	

Final qualification report:	Available upon request
First samples available:	Upon request
Intended start of delivery:	12-January-2021 or earlier upon customer approval

If you have any questions, please do not hesitate to contact your local Sales office.

PCN N° 18-059A



Title Change of Wafer Production from Infineon Technologies (Temecula) to Vanguard International Semiconductor and Infineon Technologies (Kulim) and leadframe change for Gen6.2 IGBT in

TO247 packages

Sales name	SP number	OPN	Package
AUIRGP4062D	SP001511212	AUIRGP4062D	PG-TO247-3-904
AUIRGP4062D-E	SP001511902	AUIRGP4062D-E	PG-TO247-3-904
AUIRGP4063D	SP001512458	AUIRGP4063D	PG-TO247-3-904
AUIRGP4063D-E	SP001512018	AUIRGP4063D-E	PG-TO247-3-904
AUXHKGP4062D-E	SP001662772	AUXHKGP4062D-E	PG-TO247-3-904
AUXVNGP4062D-E	SP001511846	AUXVNGP4062D-E	PG-TO247-3-904